

AEC-Q101 Qualified

V <sub>DSS</sub>	-45V
R <sub>DS(on)</sub> (Max.)	155mΩ
I <sub>D</sub>	-4.5A
P <sub>D</sub>	15W

## Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating ; RoHS compliant
- 6) 100% Avalanche tested

#### Application

Switching Power Supply

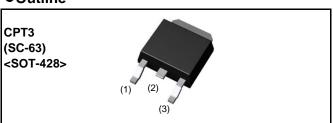
Automotive Motor Drive

Automotive Solenoid Drive

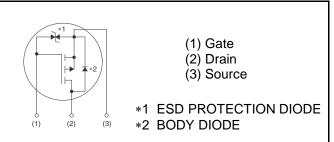
# •Absolute maximum ratings $(T_a = 25^{\circ}C)$

#### Parameter Symbol Value Unit Drain - Source voltage $V_{\text{DSS}}$ V -45 Ι<sub>D</sub><sup>\*1</sup> $T_c = 25^{\circ}C$ ±4.5 А Continuous drain current $I_D^{*1}$ $T_{c} = 100^{\circ}C$ $\pm 2.4$ А \*2 Pulsed drain current ±9.0 А I<sub>D,pulse</sub> $\mathsf{V}_{\mathsf{GSS}}$ V Gate - Source voltage ±20 \*3 14.3 Avalanche energy, single pulse mJ E<sub>AS</sub> \*3 Avalanche current -4.5А $I_{AR}$ $T_c = 25^{\circ}C$ $P_D$ 15 W Power dissipation $T_a = 25^{\circ}C$ $P_{D}$ 0.85 W T<sub>i</sub> °C Junction temperature 150 T<sub>stg</sub> °C Range of storage temperature -55 to +150

#### ●Outline



# Inner circuit



#### Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Type	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	046P05

# RSD046P05FRA

#### •Thermal resistance

Parameter	Symbol	Values			Unit
Faralleter	Symbol	Min.	Тур.	Max.	Onit
Thermal resistance, junction - ambient	R <sub>thJC</sub>	-	-	8.33	°C/W

# •Electrical characteristics( $T_a = 25^{\circ}C$ )

Deremeter	Symbol	Conditions		Values		Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -1mA$	-45	-	-	V
		$V_{DS} = -45V, V_{GS} = 0V$	_	_	1	
Zoro gato voltago drain curront	1	T <sub>j</sub> = 25°C	-	-	-1	μA
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = -45V, V_{GS} = 0V$	_	-	-100	
		T <sub>j</sub> = 125°C	-			
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μA
Gate threshold voltage	$V_{GS (th)}$	$V_{DS} = -10V, I_{D} = -1mA$	-1	-	-3	V
	R <sub>DS(on)</sub> *4	$V_{GS} = -10V, I_{D} = -4.5A$	-	110	155	
		$V_{GS} = -4.5V, I_D = -4.5A$	-	160	225	
Static drain - source on - state resistance		$V_{GS} = -4.0V, I_{D} = -4.5A$	-	185	260	mΩ
		$V_{GS} = -10V, I_D = -4.5A$		- 180	250	
		T <sub>j</sub> = 125°C	-		250	
Forward transfer admittance	<b>g</b> <sub>fs</sub>	$V_{DS} = -10V, I_{D} = -4.5A$	3	6	-	S

# •Electrical characteristics( $T_a = 25^{\circ}C$ )

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	550	-	
Output capacitance	C <sub>oss</sub>	$V_{DS} = -10V$	-	100	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	50	-	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq -25V, V_{GS} = -10V$	-	8	-	
Rise time	t <sub>r</sub> *4	$I_{\rm D} = -2.0$ A	-	8	-	20
Turn - off delay time	t <sub>d(off)</sub> *4	R <sub>L</sub> = 12Ω	-	35	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	8	-	

# •Gate Charge characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
Farameter			Min.	Тур.	Max.	Offic	
Total gate charge	$Q_g^{*4}$	$V_{DD} \simeq -25V$	-	12	-		
Gate - Source charge	$Q_{gs}^{*4}$	I <sub>D</sub> = -4.5A	-	2.2	-	nC	
Gate - Drain charge	$Q_{gd}$ *4	$V_{GS} = -5V$	-	2.2	-		
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq -30V, \ I_D = -4.5A$	-	-3.4	-	V	

# ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

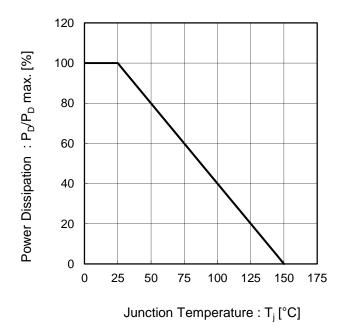
Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous source current	ا <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	6	-4.5	А
Pulsed source current	$I_{SM}$ *2	1 <sub>c</sub> = 25 C	-	-	-9	А
Forward voltage	$V_{SD}$ *4	$V_{GS} = 0V, I_{S} = -4.5A$	-	-	-1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = -4.5A	-	40	-	ns
Reverse recovery charge	$Q_{rr}^{*4}$	di/dt = -100A/µs	-	60	-	μC

\*1 Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

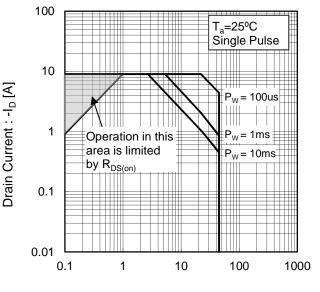
\*3 L  $\simeq$  1mH, V<sub>DD</sub> = -25V, Rg = 10 $\Omega$ , starting T<sub>j</sub> = 25°C

\*4 Pulsed



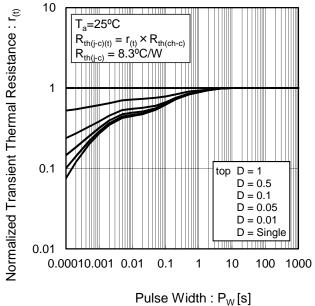
# Fig.1 Power Dissipation Derating Curve

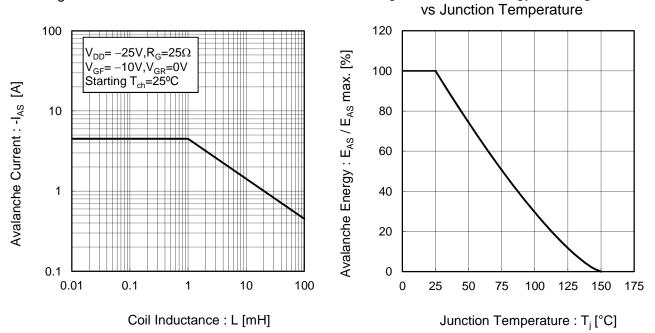
Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V<sub>DS</sub> [V]

# Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width





# Fig.4 Avalanche Current vs Inductive Load

# Fig.6 Typical Output Characteristics(I)

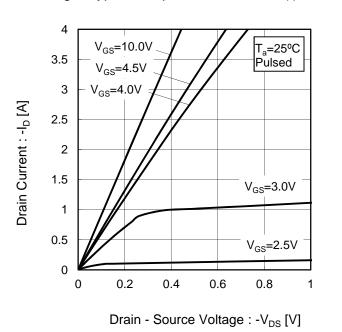
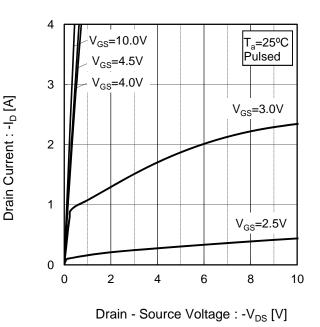


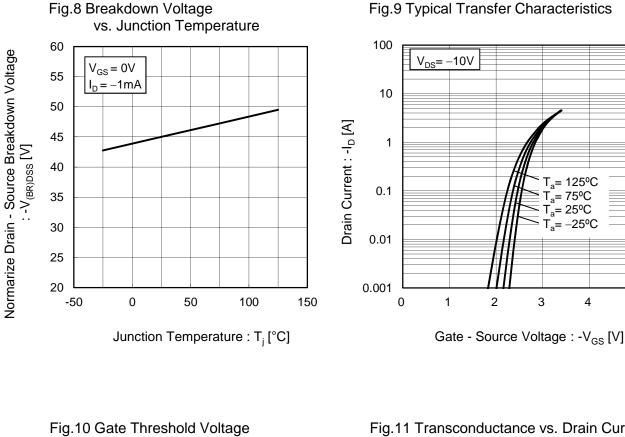
Fig.7 Typical Output Characteristics(II)

Fig.5 Avalanche Energy Derating Curve

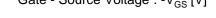


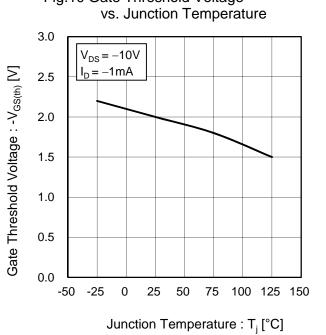
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# Electrical characteristic curves

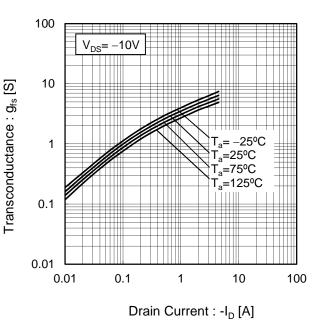


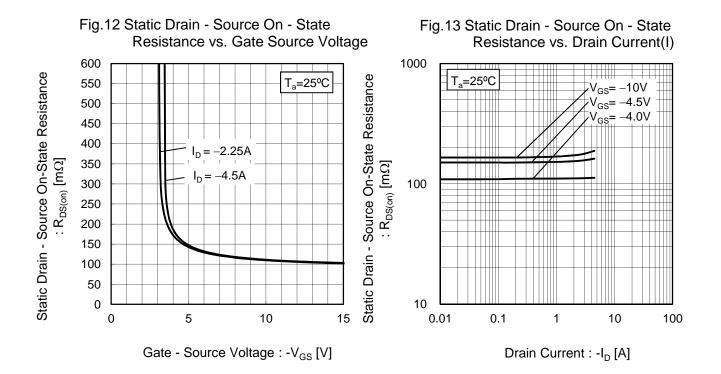
#### Fig.9 Typical Transfer Characteristics

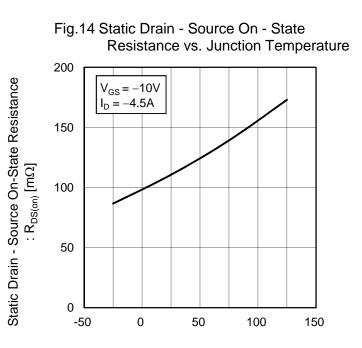




#### Fig.11 Transconductance vs. Drain Current

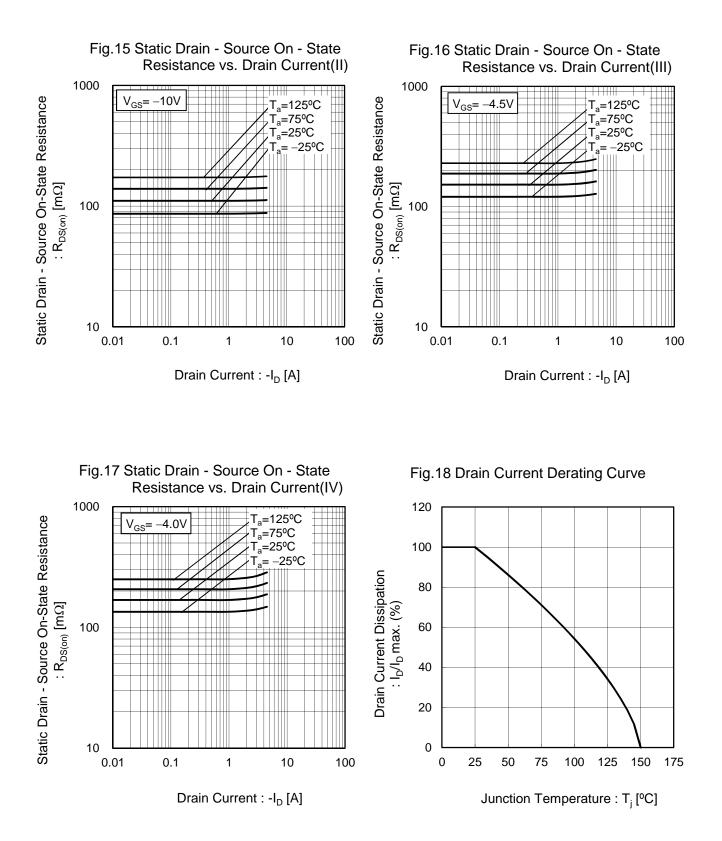






Junction Temperature : T<sub>j</sub> [°C]

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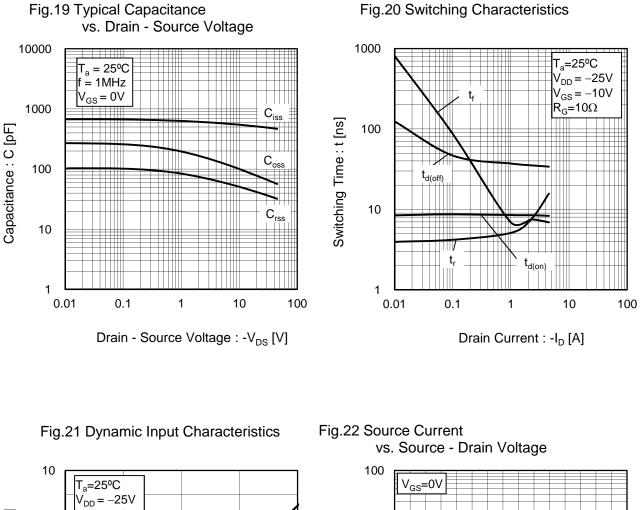
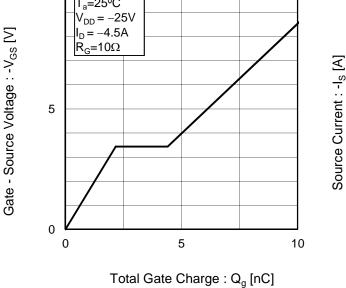
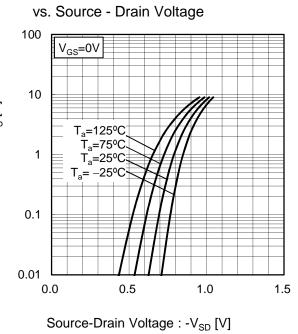
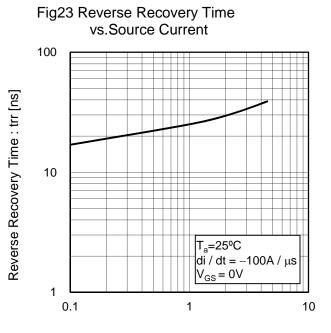


Fig.20 Switching Characteristics







Source Current : -I<sub>S</sub> [A]

#### •Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

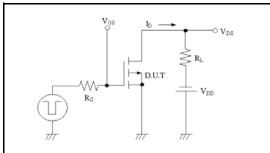


Fig.2-1 Gate Charge Measurement Circuit

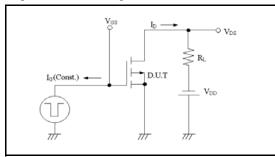
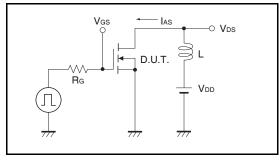


Fig.3-1 Avalanche Measurement Circuit



#### Fig.1-2 Switching Waveforms

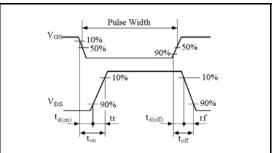


Fig.2-2 Gate Charge Waveform

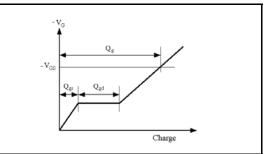
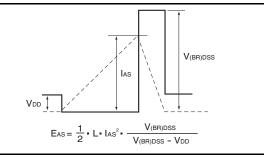
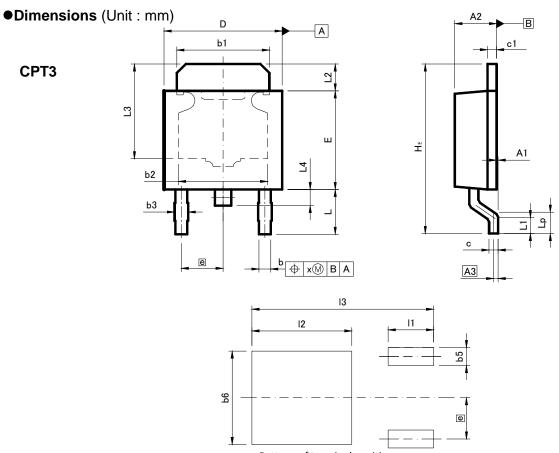


Fig.3-2 Avalanche Waveform





Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES	
DIN	MIN	MAX	MIN	MAX	
A1	0.00	0.15	0.000	0.006	
A2	2.20	2.50	0.087	0.098	
A3	0.	25	0.0	10	
b	0.55	0.75	0.022	0.030	
b1	5.00	5.30	0.197	0.209	
b2	5.	00	0.1	97	
b3	0.	75	0.0	30	
С	0.40	0.60	0.016	0.024	
c1	0.40	0.60	0.016	0.024	
D	6.30	6.70	0.248	0.264	
E	5.40	5.80	0.213	0.228	
е	2.	30	0.0	)1	
HE	9.00	10.00	0.354	0.394	
L	2.20	2.80	0.087	0.110	
L1	0.80	1.40	0.031	0.055	
L2	1.20	1.80	0.047	0.071	
L3	5.30		0.209		
L4	0.	0.90		0.035	
Lp	1.00	1.60	0.039	0.063	
х	_	0.25	-	0.010	

DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
b5	-	1.00	-	0.04
b6	-	5.20	-	0.205
1	-	2.50	-	0.098
12	-	5.50	-	0.217
13	_	10.00	_	0.394

Dimension in mm / inches

# Notice

#### Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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CLASSII	CLASSII	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSII

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:

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[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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QR code printed on ROHM Products label is for ROHM's internal use only.

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